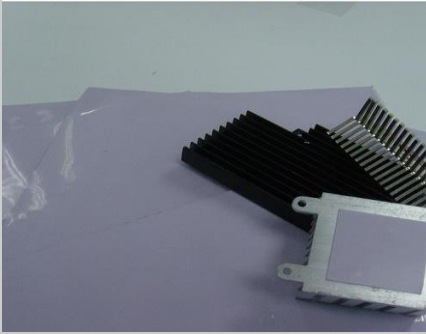


High THERMAL CONDUCTIVE GAP FILLER 5.0W/m-K

Features and Benefits

- Superior thermal performance
- 5.0W/m-K thermal conductivity
- Electrically isolating
- RoHS compliant
- Halogen-free



Typical Applications

- Notebook Computers
- Handheld Portable Electronics
- Micro Heat Pipe assemblies
- Micro Processors, Memory Chips and Graphic Processors
- Motor Control
- Wireless Communication Hardware

Optional Configurations

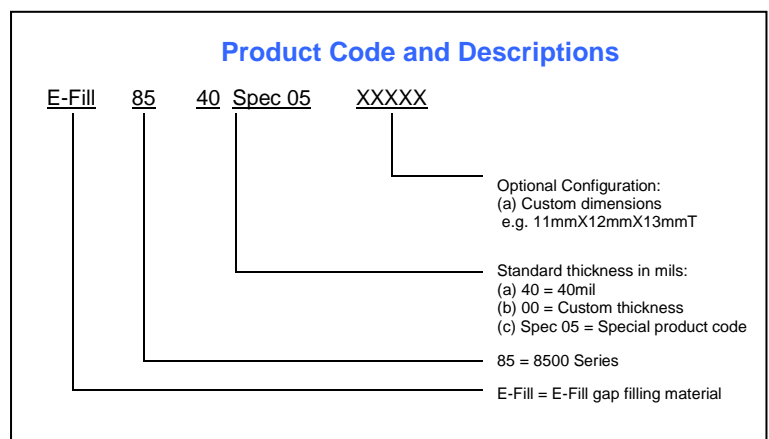
- Can be die-cut into other dimensions

E-Fill 8500Spec05 SE offers good thermal performance and conformability. This material conforms to surface irregularities under low application pressures. It is electrically non-conductive and naturally tacky. Additional adhesive is generally not required.

The proprietary formulation of E-Fill 8500Spec05 SE is RoHS compliant and halogen-free, providing extra reassurance in applications where hazardous substances are forbidden.

Properties	E-Fill 8500Spec05 SE	Test Method
Construction & Composition	Soft silicone elastomer	—
Color	Violet	Visual
Thickness Range /inch (mm)	0.02"~0.40" (0.508~10.16) in 0.01" (0.254) increments	—
Standard Sheet Size	12" x 16"	—
Density /g.cm ⁻³	3.3	—
Hardness /Shore 00	35	ASTM D2240
Tensile Strength /psi	34	ASTM D412
UL Flammability Rating	UL94 V0 standard	—
Temperature Range /°C	-40°C~200°C	—
Thermal Conductivity /W.m ⁻¹ .K ⁻¹	5.0	ASTM D5470 (modified)
Breakdown Voltage /V	>4000 (Thickness = 0.02~0.04") >6000 (Thickness ≥ 0.04")	ASTM D149
Volume Resistivity /ohm.cm	8. 0 x 10 ¹³	ASTM D257
Dielectric Constant @ 1MHz	12.8	ASTM D150
Shelf Life	24 months	—
Please contact us for other special requirements		

Carrier Treatment	Criteria
Fiber Glass (FG)	Not Recommended
Rubberized Cloth (RC)	Not Recommended
Pressure Sensitive Adhesive (PSA)	Not Recommended
Detachable Adhesive (DA)	Not Recommended
Aluminum Foil (AL)	Not Recommended
Kapton (PI)	Not Recommended
Talc treatment (DAT)	Not Recommended



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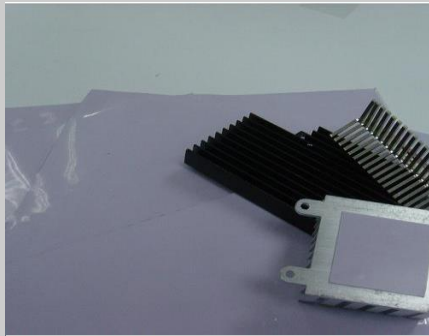
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产品特点

- 出众的导热性能
- 导热率 5.0W/m-K
- 电绝缘
- 符合 RoHS 规格
- 无卤素



一般应用

- 电子笔记本
- 手提电子器材
- 微热管组件
- 微处理器，内存芯片，图形处理器
- 底盘，框架或其他散热组件
- 电机控制器
- 通信用硬件

其他配置

- 可模切成特定尺寸

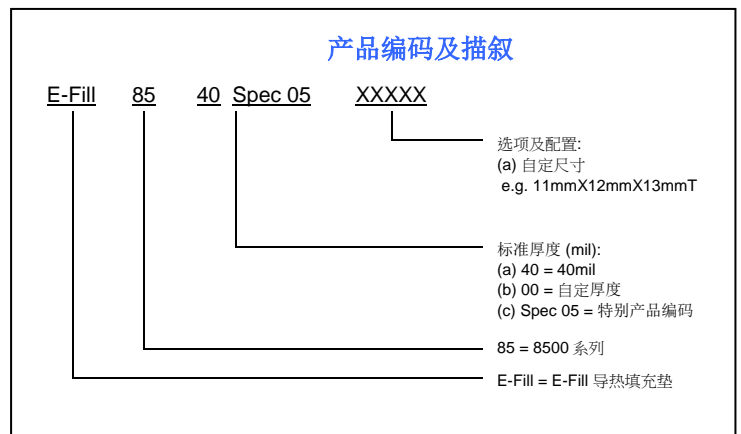
E-Fill 8500Spec05 SE 是一种拥有良好表面吻合度和高导热效能的导热填充垫，这款导热填充垫能够在低应用压力的情况下保持不规则表面间的良好接触。E-Fill 8500Spec05 SE 具有电绝缘及天然粘性等特点，在正常情况下不需要增加额外的胶粘剂

独有的产品配方不单指符合 RoHS 规格更达到无卤素要求，令客户在使用时对于有害物质的控制更有信心。

一般特性	E-Fill 8500Spec05 SE	测试方法
结构及主要成分	硅树脂弹性体	—
颜色	紫色	目测
厚度 /inch (mm)	0.02"~0.40" (0.508~10.16) 以 0.01" (0.254)为基本增量单位	—
标准片材尺寸	12" x 16"	—
密度 /g.cm ⁻³	3.3	—
硬度 /Shore 00	35	ASTM D2240
拉伸强度 /psi	34	ASTM D412
UL 燃烧等级	UL-94-V0	—
使用温度 /°C	-40°C~200°C	—
导热率 W.m ⁻¹ .K ⁻¹	5.0	ASTM D5470 (modified)
击穿电压/V	>4000 (厚度 = 0.02~0.04") >5000 (厚度 ≥ 0.04")	ASTM D149
体积电阻率 /ohm.cm	8.0 x 10 ¹³	ASTM D257
介电常数@ 1MHz	12.8	ASTM D150
有效期	24 months	—

如对产品有特殊要求，请联络我们

载体	标准
玻璃纤维 (FG)	不建议使用
胶布 (RC)	不建议使用
压敏胶 (PSA)	不建议使用
不粘胶 (DA)	不建议使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	不建议使用



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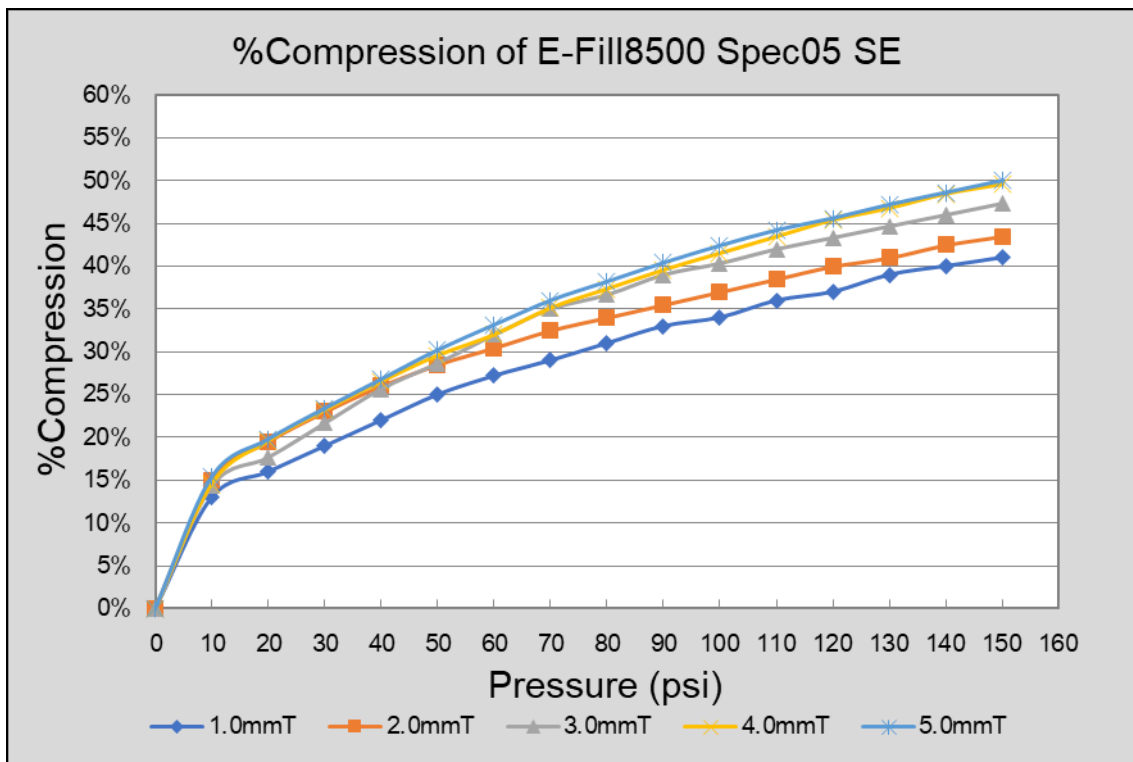
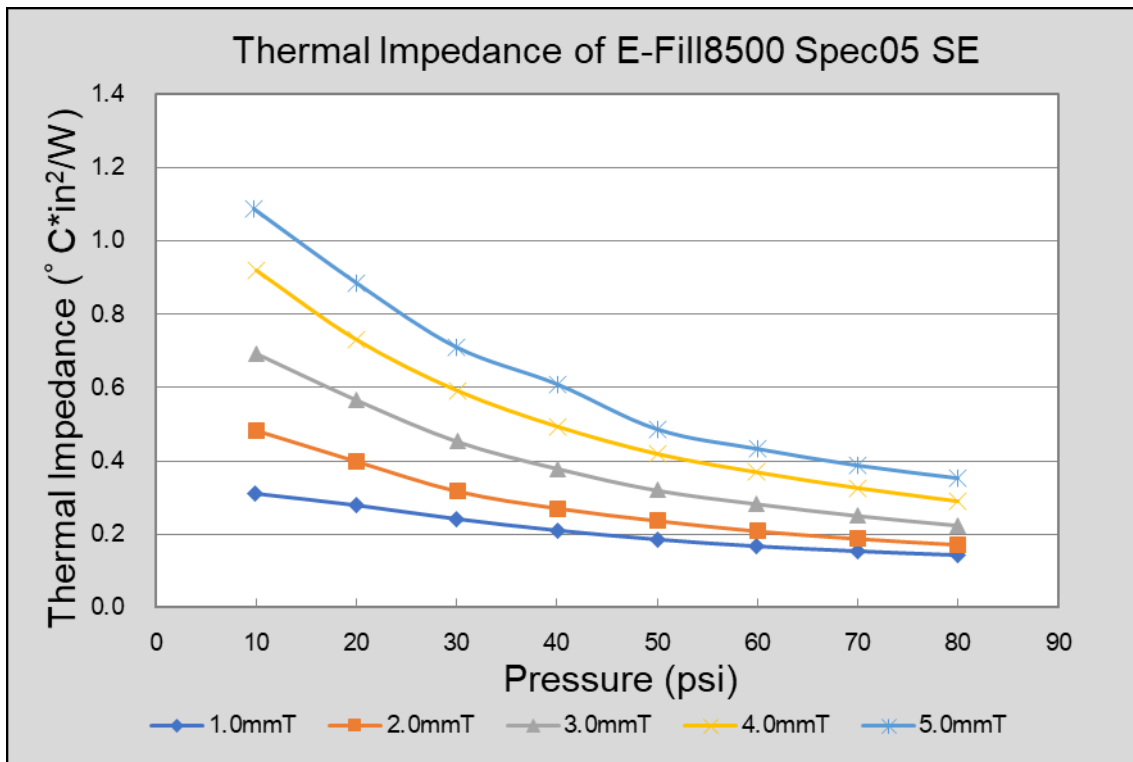
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